

Challenges of Microwave Assembly

Speaker: Jay Chudasama – Agile Microwave Technology Inc., Hicksville, NY 11801

E-Mail: jayc@agilemwt.com

Abstract

RF and Microwave Hybrids, “Microwave Integrated Circuits” (MIC), RF and Microwave modules, Monolithic Microwave Integrated Circuits, MMIC all require a unique set of materials and processes necessary to achieve reliable operations in extreme military and commercial environments. This presentation will examine some of the critical challenges and aspects of “microwave packaging” from a practical perspective and compare to “Low electrical frequency” circuit manufacturing”.

Valuable lessons learned from years of experience, design issues, material tradeoffs, process selection are covered in detail with the goal of imparting useful information to assemble and manufacture reliable microwave hybrids for military, space, and other high reliability commercial and medical device applications.

Speaker:

Jay Chudasama, GM/President
Agile Microwave Technology Inc.
101 Bloomingdale Road
Hicksville, NY 11801

<http://agilemwt.com>